

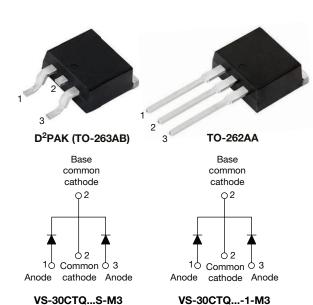
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Vishay Semiconductors

HALOGEN

FREE

High Performance Schottky Rectifier, 2 x 15 A



PRIMARY CHARACTERISTICS					
I _{F(AV)}	2 x 15 A				
V _R	80 V, 100 V				
V _F at I _F	0.67 V				
I _{RM}	7.0 mA at 125 °C				
T _J max.	175 °C				
E _{AS}	7.5 mJ				
Package	D ² PAK (TO-263AB), TO-262AA				
Circuit configuration	Common cathode				

FEATURES

- 175 °C T_J operation
- · Center tap configuration
- · Low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

This center tap Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS									
SYMBOL CHARACTERISTICS VALUES UNITS									
I _{F(AV)}	Rectangular waveform	30	А						
V _{RRM}		80/100	V						
I _{FSM}	t _p = 5 μs sine	850	А						
V _F	15 A _{pk} , T _J = 125 °C (per leg)	0.67	V						
T _J	Range	-55 to +175	°C						

VOLTAGE RATINGS						
PARAMETER	SYMBOL	VS-30CTQ080S-M3 VS-30CTQ080-1-M3	VS-30CTQ100S-M3 VS-30CTQ100-1-M3	UNITS		
Maximum DC reverse voltage	V_{R}	80	100	V		
Maximum working peak reverse voltage	V_{RWM}	00	100	V		



VS-30CTQ...S-M3, VS-30CTQ...-1-M3 Series

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ABSOLUTE MAXIMUM RATINGS									
PARAMETER	PARAMETER		TEST COND	ITIONS	VALUES	UNITS			
Maximum average per device					30				
forward current See fig. 5	per leg	I _{F(AV)}	50 % duty cycle at T _C = 129 °C, rectangular waveform		15	Α			
Maximum peak one cycle	non-repetitive		5 μs sine or 3 μs rect. pulse	Following any rated load	850	_ ^			
surge current per leg See fig. 7		I _{FSM}	10 ms sine or 6 ms rect. pulse	condition and with rated V _{RRM} applied	275				
Non-repetitive avalanche energy per leg		E _{AS}	$T_J = 25 ^{\circ}\text{C}, I_{AS} = 0.50 \text{A}, L = 60 \text{mH}$		7.50	mJ			
Repetitive avalanche current per leg		I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _B typical		0.50	Α			

ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS				
		15 A	T _{.1} = 25 °C	0.86	V		
Maximum forward voltage drop per leg See fig. 1	V _{FM} ⁽¹⁾	30 A	11 = 25 0	1.05			
		15 A	T _J = 125 °C	0.67			
		30 A	1J = 125 C	0.82			
Maximum reverse leakage current per leg	. (1)	T _J = 25 °C	V Detect V	0.55	A		
See fig. 2	I _{RM} ⁽¹⁾	T _J = 125 °C	V _R = Rated V _R	7.0	- mA		
Maximum junction capacitance per leg	C _T	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		500	pF		
Typical series inductance per leg	L _S	Measured lead to lead 5 r	8.0	nH			
Maximum voltage rate of change	dV/dt	Rated V _R	10 000	V/µs			

Note

 $^{^{(1)}\,}$ Pulse width < 300 µs, duty cycle < 2 %

THERMAL - MECHAN	THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Maximum junction and storage temperature range	Maximum junction and storage temperature range			-55 to 175	°C				
Maximum thermal resistance, junction to case per leg		В	DC operation	3.25	°C/W				
Maximum thermal resistance, junction to case per package		R _{thJC}	DC operation	1.63	C/VV				
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased	0.50					
Approximate weight				2	g				
Approximate weight				0.07	OZ.				
May arting toway	minimum			6 (5)	kgf · cm				
Mounting torque maximui				12 (10)	(lbf · in)				
Maulina davisa			Case style D ² PAK (TO-263AB)	30CTC 30CTC					
Marking device	ng device		Case style TO-262AA	30CTC					

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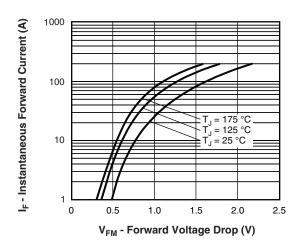


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

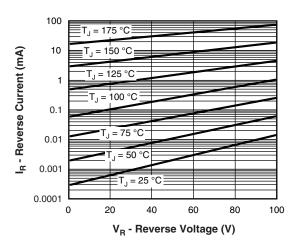


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

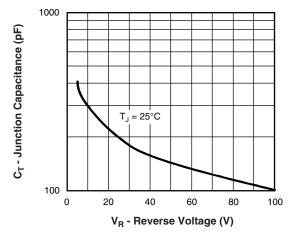


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

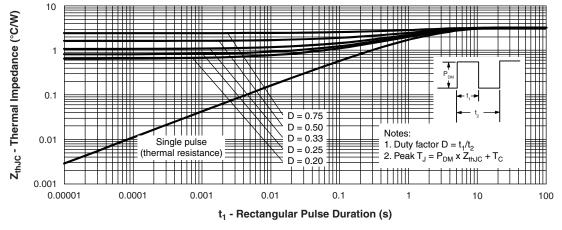


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

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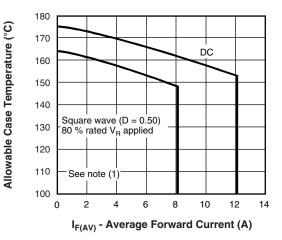


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

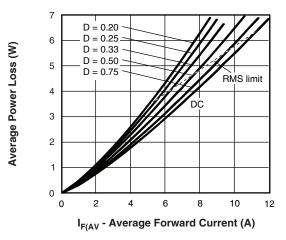


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

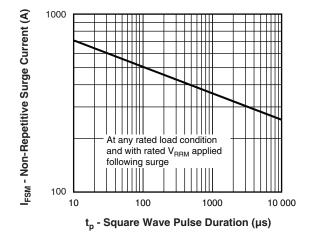


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

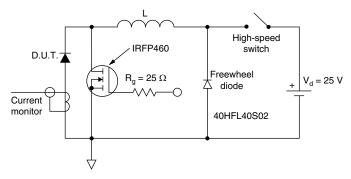


Fig. 8 - Unclamped Inductive Test Circuit

Note

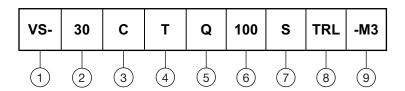
 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D)}; I_R \text{ at } V_{R1} = 10 \text{ V}. \end{array}$

VS-30CTQ...S-M3, VS-30CTQ...-1-M3 Series

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (30 A)

3 - Circuit configuration: C = common cathode

4 - T = TO-220

Schottky "Q" series

080 = 80 V 100 = 100 V

7 - • S = D^2PAK (TO-263AB)

• -1 = TO-262AA

8 - • None = tube

• TRL = tape and reel (left oriented - for D2PAK (TO-263AB) only)

• TRR = tape and reel (right oriented - for D²PAK (TO-263AB) only)

9 - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-30CTQ080S-M3	50	Antistatic plastic tubes					
VS-30CTQ080STRL-M3	800	13" diameter plastic tape and reel					
VS-30CTQ080STRR-M3	800	13" diameter plastic tape and reel					
VS-30CTQ100S-M3	50	Antistatic plastic tubes					
VS-30CTQ100STRL-M3	800	13" diameter plastic tape and reel					
VS-30CTQ100STRR-M3	800	13" diameter plastic tape and reel					
VS-30CTQ080-1-M3	50	Antistatic plastic tubes					
VS-30CTQ100-1-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS					
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164			
Differsions	TO-262AA	www.vishay.com/doc?96165			
Dout moulting information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444			
Part marking information	TO-262AA	www.vishay.com/doc?95443			
Packaging information		www.vishay.com/doc?96424			



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES		SYMBOL	SYMPOL MILLIMETERS		ERS INCHES		NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

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TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	METERS	INC	INCHES			
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
E	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54 BSC		0.100	BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.36	3.71	0.132	0.146			

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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